# Time-Lag Brick SMD Fuse 2611





# RoHS Compliant

# **Description**

The brick fuse for the small size and good electrical performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics during use and also makes our brick fuses more heat and shock tolerant than typical brick fuses.

### **Applications**

Time-lag type brick fuse for over-current protection.

### **Features**

- · Rapid interruption of excessive current
- · Compatible with reflow and wave soldering
- · Ceramic body and silver plated copper terminal
- Excellent environmental integrity
- Lead-free and Halogen-free
- Designed to UL 248-14

### **Specifications**

Operating Temperature : -55°C to +125°C Storage Conditions : +10°C to +60°C

Relative Humidity : ≤ 75% yearly average without dew, maximum 30 days at 95%

Vibration Resistance : 24 cycles at 15 min. each

10-60Hz at 0.75mm amplitude 60-2000Hz at 10g acceleration

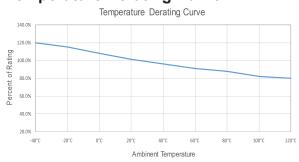
### **Electrical Characteristics**

Part Number	Rated Current	Max. Voltage	Typical Voltage Drop (mV)	Breaking Capacity	Typical Melting I²t (A²sec)	Typical Cold Resistance (Ω)
MP001614	1A	250V AC 125V AC	300	100A@250V AC 100A@125V AC 50A@125V DC	0.87	0.256

#### Note:

- (1) Permissible continuous operating current is ≤100% at ambient temperature of 23°C (73.4°F)
- (2) The current values used for calculating I<sup>2</sup>T should be within the standard 10In.

### **Temperature Derating Curve**



Calculation for ideal fuse selection =

Operating Current (A)
Rating (% × 0.75)

16/12/19 V1.0

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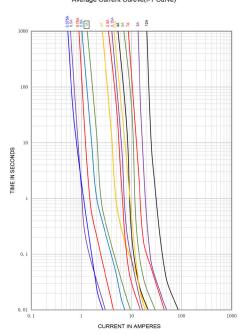
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#### **Time vs Current Characteristics Table**

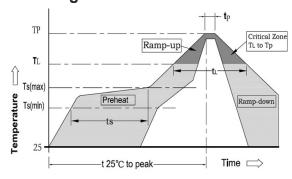
#### Average Time Current (I-T) Curves

Average Current Cureve(I-T Curve)



Time vs Current Characteristics: UL-248-14					
Rated Current	100%	200%			
1A	>4h	<120s			

## **Soldering Parameters**



1. Infrared Reflow:

Temperature: 260°C Time: 5sec Max.

2. Wave Soldering:

Reservoir Temperature: 260°C Time in Reservoir: 10sec Max.

3. Hand Soldering

Temperature: 300°C Time: 3 sec. Max.

Soldering iron avoid touch Brass Cap.

	Profile Feature	Pb-Free Assembly
Average Ramp-UP Rate(Tsmax to Tp)		3°C/s Max.
Preheat	Temperature Min (Ts min)	150°C
	Temperature Max (Ts max)	200°C
	Time (Tsmin to Ts max)	60sec to 120sec
Peak Temperature (TP)		260°C
Time within 5°C of actual Peak Temperature(TP)		5sec
Melting tin time (TL)		20sec to 40sec
Ramp-Down Rate		6°C/s Max.
Time 25°C to Peak Temperature(TP)		8 minutes Max.

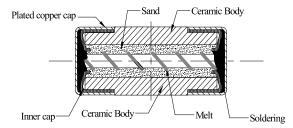
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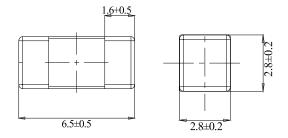
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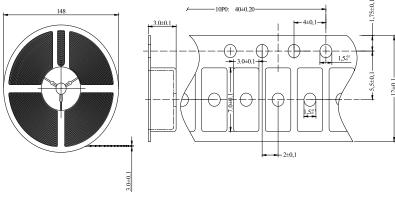
### **Mechanical Specifications**



# Diagram



# **Packing Information**



Dimensions: Millimetres

### **Part Number Table**

Description	Part Number
Brick SMD Fuse, Time-Lag, 1A, 250V AC, 2611	MP001614

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